

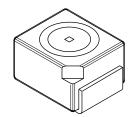
PACKAGE DIMENSIONS 0.083 (2.1) 0.067 (1.7) 0.102 (2.6) 0.091 (2.3) 0.083 (2.1) .041 (0.1) 0.035 (0.9) 0.028 (0.7) 0.134 (3.4) 0.094 (2.4) 0.043 (1.1) 0.020 (0.5) CATHODE 0.024 (0.6) 0.007 (.18) 0.005 (.12) NOTE:

Dimensions for all drawings are in inches (mm).

SUPER BRIGHT RED SUPER BRIGHT ORANGE SUPER BRIGHT YELLOW QTLP670C-R QTLP670C-E QTLP670C-Y

FEATURES

- Non-diffused package excellent for back-lighting and coupling to light pipe
- · Low package profile
- AllnGaP technology
- Wide viewing angle of 120°



DESCRIPTION

This surface mount lamp is designed with a flat top and sides for automatic placement equipment. It is compatible with convective IR and vapor phase reflow soldering and conductive epoxy attachment process. The package size and configuration conform to EIA-535 BAAC standard specification for case size 3528 tantalum capacitor.

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise specified)						
Parameter	Symbol	Rating	Unit			
Operating Temperature	T _{OPR}	-40 to +100	°C			
Storage Temperature	T _{STG}	-40 to +100	°C			
Lead Soldering Time	T _{SOL}	260 for 5 sec	°C			
Continuous Forward Current	I _F	30	mA			
Peak Forward Current (f = 1.0 KHz, Duty Factor = 1/10)	I _F	160	mA			
Reverse Voltage (I _R = 10 μA)	V _R	5	V			
Power Dissipation	P _D	100	mW			

ELECTRICAL / OPTICAL CHARACTERISTICS (TA =25°C)					
Part Number	QTLP670C-R	QTLP670C-E	QTLP670C-Y	Condition	
Luminous Intensity (mcd)				$I_F = 20mA$	
Minimum	40	40	40		
Typical	70	70	70		
Forward Voltage (V)				$I_F = 20mA$	
Maximum	2.4	2.8	2.8		
Typical	1.9	2.1	2.1		
Wavelength (nm)				$I_F = 20mA$	
Peak	630	620	590		
Dominant	623	615	589		
Spectral Line Half Width (nm)	20	18	15	$I_F = 20mA$	
Viewing Angle (°)	120	120	120	$I_F = 20mA$	



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TYPICAL PERFORMANCE CURVES

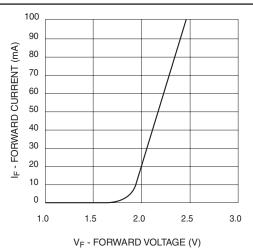


Fig. 1 Forward Current vs. Forward Voltage

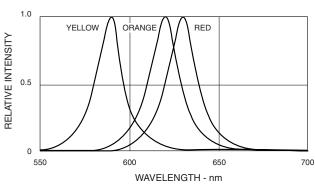


Fig. 3 Relative Intensity vs Peak Wavelength

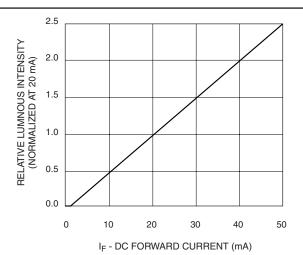


Fig. 2 Relative Luminous Intensity vs. DC Forward Current

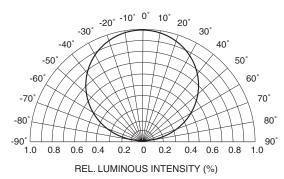


Fig.4 Radiation Diagram

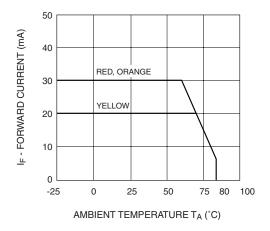
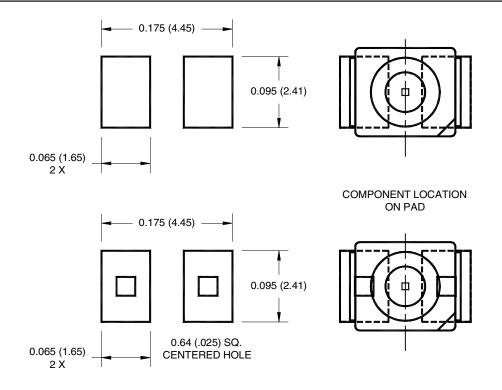


Fig.5 Forward Current vs. Ambient Temperature

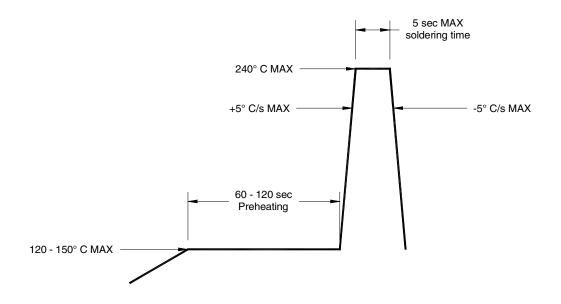


SUPER BRIGHT RED QTLP670C-R SUPER BRIGHT ORANGE QTLP670C-E SUPER BRIGHT YELLOW QTLP670C-Y

RECOMMENDED PRINTED CIRCUIT BOARD PATTERN



RECOMMENDED IR REFLOW SOLDERING PROFILE





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